Supply Chain Explorer

By the Emerging Technology Observatory

This is an export from the ETO Supply Chain Explorer, available at: https://chipexplorer.eto.tech You can see the web version of this content at https://chipexplorer.eto.tech/?filter-choose=input-resource=N72.

Bonding tools

Bonding tools include die attach tools (to connect dies to lead frames or substrates), wire bonders (to make interconnects between lead frames and die pads), and advanced interconnect tools.